

Protective & assembly products for electronics industry

HERNON

The rapid changes in size and complexity of modern electronics pose demanding challenges and expectations for developers and manufacturers. Herson products bridge this gap with its focus on ensuring protection from stresses and damage while enhancing manufacturing processes.



Board Level Protection

Herson's potting, conformal coating and encapsulation compounds ensure utmost protection of the printed circuit board from impact, thermal cycling, corrosion and even security breaches.

	Polyurea TM 744	UCC TM 739	Silastomer TM 330	Epoxy 325	Epoxy 373	Epoxy 307
Key Performance	Dual cure conformal coating	Especially clear conformal coating	Self leveling potting	Fast setting potting or encapsulation	Highly flexible potting or encapsulation	Single part cure potting or encapsulation
Color	Amber	Clear	Clear	Clear/Amber	Black/White	Tan
Viscosity, cP	300 to 600	300 to 600	480	2500	900 to 1900	120 000
Dielectric Strength, V/mil	1110	960	650	660	660	745
Hardness	60 Shore D	40 Shore D	35 Shore A	50 Shore A	65 Shore A	80 Shore D
Curing Method	UV & heat	UV	Mixture	UV & 2 part mixing	2 part mixing	Heat
Curing Schedule	5 to 15 sec at UV & 10 min @ 120°C	5 to 15 sec	Soak free: 30 min @ 25°C	Mix ratio: 1/1 Work life: 60 min	Mix ratio: 1/1 Work life: 30 min	Soak free: 10 to 12 min @ 120°C
Temperature Range, °C	-55 to 149	-55 to 121	-71 to 232	-55 to 171	-16 to 175	-55 to 175

